Please replace the paragraph on page 25 (under the heading ABSTRACT) with the

following paragraph:

-- A method and system compensating for thermally induced motion of probe cards used

in testing die on a wafer includes a probe card incorporating temperature control devices to

maintain a uniform temperature throughout the thickness of the probe card. A probe card

incorporating bi-material stiffening elements which respond to changes in temperature in such a

way as to counteract thermally induced motion of the probe card is disclosed including rolling

elements, slots and lubrication. Various elements for allowing radial expansion of a probe card

to prevent thermally induced motion of the probe card are also disclosed. A method for

detecting thermally induced movement of the probe card and moving the wafer to compensate is

also disclosed. --

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the

application:

1. (currently amended) A method for adjusting a probe card, comprising:

placing a probe card in a prober;

measuring a first distance from a know-known position to a position of said probe card;

comparing via microprocessor means said first distance to a second distance to determine

a variance therebetween; and,

Response to Office Action Serial No. 10/034,412

when said microprocessor determines said variance exceeds a determined value,

electrically signaling means for transmitting energy to said probe card to selectively deflect said

probe card to control the geometric planarity of said probe card.

2. (original) The method of claim 1 wherein said comparing and signaling are done

repetitively until said variance does not exceed said determined value.

(original) The method of claim 2 wherein said measuring is with an optical

sensor.

3.

4. (original) The method of claim 3 wherein said microprocessor is in a test head on

said prober.

5. (original) The method of claim 3 wherein said microprocessor is in a tester that is

physically separate from said prober and is connected thereto by means for data communication.

6. (original) The method of claim 3 wherein said means for transmitting energy

transmits thermal energy to said probe card.

7. (original) The method of claim 3, wherein said probe card comprises a bi-

metallic element connected thereto to impart deflection.

Response to Office Action Serial No. 10/034,412 Group Art Unit 2829 8. (original) The method of claim 1 wherein said measuring is with an optical

sensor.

9. (original) The method of claim 1 wherein said microprocessor is in a test head on

said prober.

10. (original) The method of claim 1 wherein said microprocessor is in a tester that is

physically separate from said prober and is connected thereto by means for data communication.

11. (original) The method of claim 1 wherein said means for transmitting energy

transmits thermal energy to said probe card.

12. (original) The method of claim 1, wherein said probe card comprises a bi-

metallic element connected thereto to impart deflection.

13. (original) A system for adjusting geometric planarity of a probe card, comprising:

a prober for receiving a probe card;

means for measuring a distance indicating a position of said probe card;

computer means for comparing said first distance to a second distance to determine a

variance therebetween; and,

Response to Office Action Serial No. 10/034,412 Group Art Unit 2829 means for electrically signaling in response to said variance exceeding a value, said

means for signally transmitting a signal to activate means for transmitting energy to said probe

card to selectively deflect said probe card to control the geometric planarity of said probe card.

14. (original) The system of claim 13 comprising an energy transmissive element

which is a thermal element employing thermal energy to selectively deflect a portion of said

probe card.

15. (original) The system of claim 13 and further including a temperature sensor for

monitoring temperature corresponding to deflection of said probe card.

(withdrawn) The system of claim 13 and further including a stiffening element 16.

attached to a face of said probe card and adapted to provide structural resistance to planarity

deflection of said probe card.

17. (withdrawn) The system of claim 13 and further comprising means for

facilitating radial expansion/contraction of said probe card with respect to a stiffening element.

18. (withdrawn) The system of claim 13 and further including a multi-layer element

having a first layer and a second layer, said first layer and said second layer having different

rates of expansion per unit of energy, said multi-layer element being attached to said probe card,

Response to Office Action Serial No. 10/034,412